## What is claimed is:

5

10

15

20

- 1. A method of forming a floating gate in a flash memory device, comprising the steps of:
- forming a tunnel oxide film and a first polysilicon film on a semiconductor substrate;

etching given regions of the first polysilicon film and the tunnel oxide film and then etching the exposed semiconductor substrate by a given depth, thus forming a trench;

forming an oxide film on the entire structure so that the trench is buried, and then polishing the oxide film to form an isolation film;

decomposing a native oxide film grown on the first polysilicon film, implementing an anneal process to outgas the decomposed material, and then forming a second polysilicon film; and

patterning the second polysilicon film and the first polysilicon film to form a floating gate.

- 2. The method as claimed in claim 1, further comprising the step of cleaning the surface of the first polysilicon film using a HF solution, a diluted HF solution or RCA after the isolation film is formed.
- 3. The method as claimed in claim 1, wherein decomposition of the native oxide film is to decompose  $SiH_4$  and  $SiO_2$  into Si and  $H_2$  and Si and  $O_2$  by introducing a  $SiH_4$  gas of about  $0.1 \sim 1.9$  M and reacting it for about 5

 $\sim$  20 minutes, in a state that the temperature and pressure of a reaction chamber are kept at 510  $\sim$  590 °C and 200  $\sim$  600mTorr, respectively.

- 4. The method as claimed in claim 1, wherein the anneal process is implemented by introducing a  $N_2$  gas of about  $0.1 \sim 1.9$ SLM and reacting it for  $5 \sim 20$ minutes so that a  $H_2$  gas and an  $O_2$  gas react to a  $N_2$  gas and are then outgassed, in a state that the temperature and pressure of a reaction chamber are kept at  $750 \sim 950$ °C and  $100 \sim 300$ mTorr, respectively.
- 5. The method as claimed in claim 1, wherein the second polysilicon film is formed by introducing a mixed gas of a SiH<sub>4</sub> gas and a PH<sub>3</sub> gas of about  $0.5 \sim 2.0$ SLM and then reacting it for  $20 \sim 40$ minutes, in a state that the temperature and pressure of a reaction chamber are kept at  $510 \sim 590$ °C and  $200 \sim 600$ mTorr, respectively.